

NCN@Purdue - Intel Summer School: July 14-25, 2008

Physics of Nanoscale Transistors: Lecture 3B:

***Theory of the
Ballistic MOSFET***

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outline

- 1) **Review**
- 2) Effective masses
- 3) Multiple subbands
- 4) 2D electrostatics
- 5) Discussion
- 6) Summary

review

1) In Lecture 3, we generalized

$$I_D = WC_{ox} (V_{GS} - V_T) \nu_T \left(\frac{1 - e^{-qV_{DS}/k_B T}}{1 + e^{-qV_{DS}/k_B T}} \right)$$

to include Fermi-Dirac statistics:

$$I_D = WC_{ox} (V_{GS} - V_T) \mathcal{E}_P \left[\frac{1 - \mathcal{F}_{1/2}(\eta_{F2}) / \mathcal{F}_{1/2}(\eta_{F1})}{1 + \mathcal{F}_0(\eta_{F2}) / \mathcal{F}_0(\eta_{F1})} \right]$$

review

2) We also discussed key device parameters for ballistic MOSFETs:

- ballistic injection velocity
- ballistic on-current
- ballistic channel resistance
- ballistic drain saturation voltage
- ballistic mobility

what approximations did we make?

- 1) semiclassical approach (no quantum transport)
- 2) used a bulk $E(k)$ within the device
- 3) assumed parabolic energy bands
- 4) ignored scattering
- 5) ...

questions

- 1) How do we treat more realistic band structures (e.g. the conduction band of Si?)
- 2) How to we treat subthreshold conduction and 2D electrostatics?

These questions are addressed in this lecture (Part 2)

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about effective masses

$$N_{2D} = \frac{m^* k_B T}{\pi \hbar^2} \text{ \#/cm}^2$$

$$\mathcal{G}_T \equiv \sqrt{\frac{2k_B T}{\pi m^*}} \frac{\mathcal{F}_{1/2}(\eta_{F1})}{\mathcal{F}_0(\eta_{F1})}$$

For carrier densities, we should use a density-of-states effective mass.

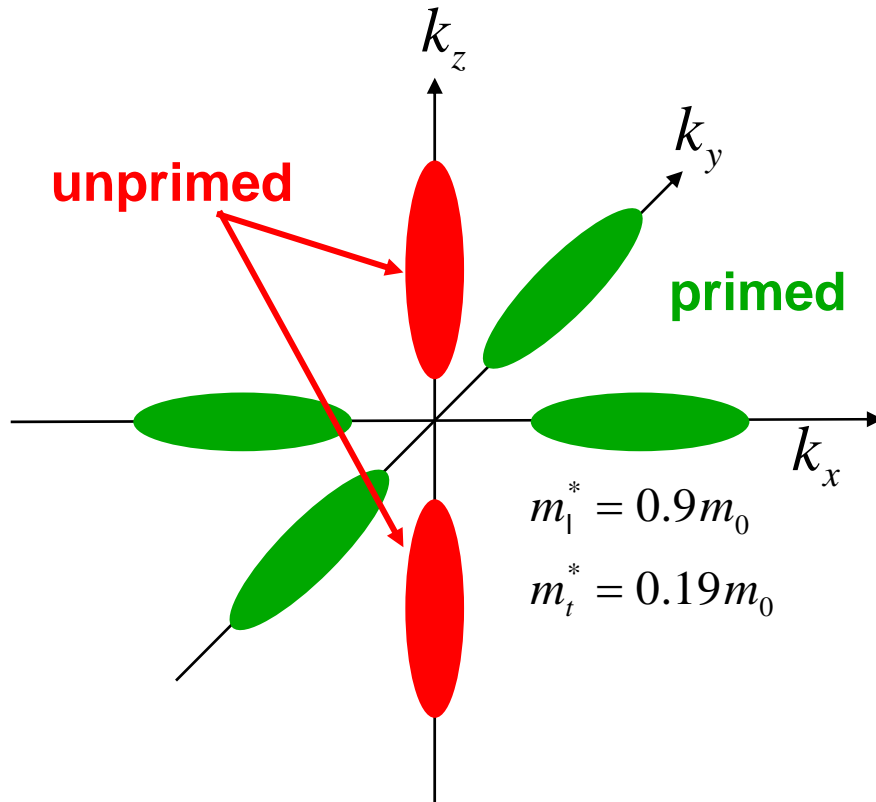
For velocities we should use a conductivity effective mass.

The values of these masses depend on the material and the channel orientation.

Let's work this out for the simplest case: (100) Si.

example: (100) Silicon

Si conduction band

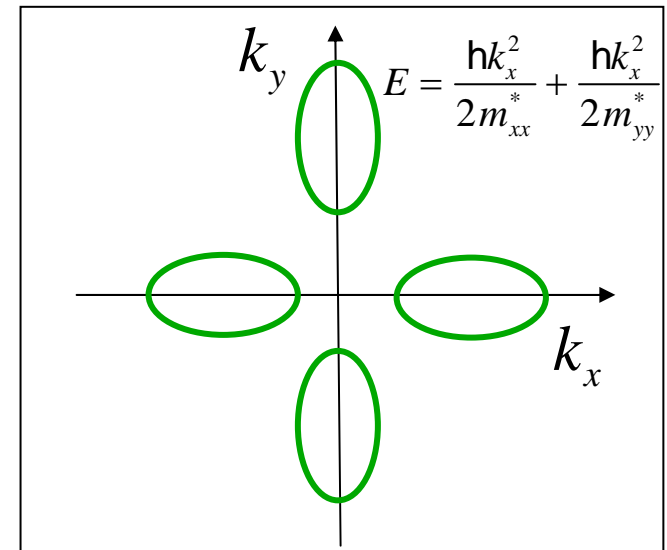
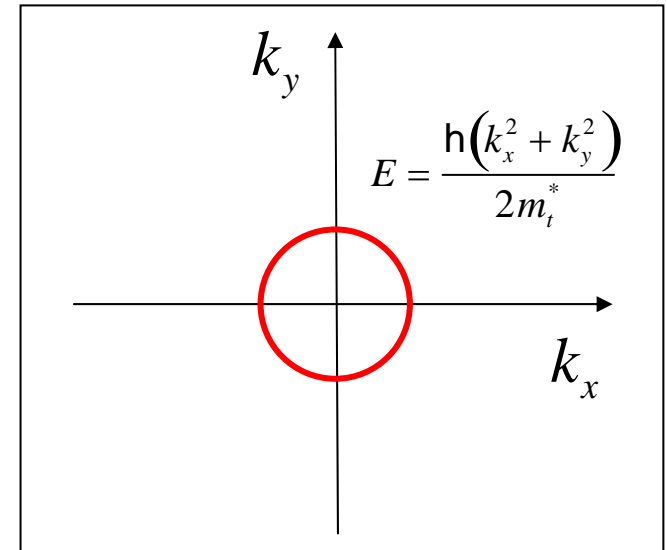


$$m_1^* = 0.9m_0$$

$$m_t^* = 0.19m_0$$

confinement masses: $m_{conf}^* = m_{zz}^*$

unprimed: $m_{conf}^* = m_1^*$ primed: $m_{conf}^* = m_t^*$



example: ellipsoidal energy bands

To see how we determine the DOS and conductivity effective masses, let's re-examine our derivation from the beginning - with the drain current:

$$I_D = \frac{2q}{h} \int_{\varepsilon_1(0)}^{\infty} M(E)(f_1 - f_2) dE$$

So we begin with $M(E)$.

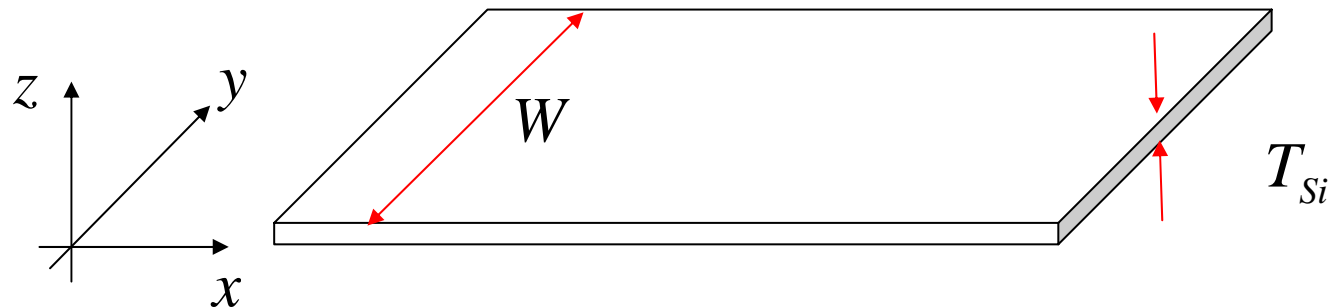
conducting channels: (100) Si [100] transport

$$g_{1D}(E) = g_V \times \frac{1}{\pi\hbar} \sqrt{\frac{m_{yy}^*}{2[E - \varepsilon_1(0)]}} \quad \text{\#/eV-cm}$$

(Divided by 2 to account for the fact the spin has already been included in the current formula.)

$$M(E) = W \int_{\varepsilon_1(0)}^E g_{1D}(E) dE = W g_V \frac{\sqrt{2m_{yy}^* [E - \varepsilon_1(0)]}}{\pi\hbar}$$

$M(E)$ = number of transverse modes in the y -direction with cut-off energy less than E .



current: (100) Silicon [100] transport

To find the drain current, we integrate:

$$I_D = \frac{2q}{h} \int_{\varepsilon_1(0)}^{\infty} M(E)(f_1 - f_2) dE$$

$$I_D = Wqg_V \left(\frac{m_{yy}^* k_B T}{2\pi\hbar^2} \right) \sqrt{\frac{2k_B T}{\pi m_{yy}^*}} \left[\mathcal{F}_{1/2}(\eta_{F1}) - \mathcal{F}_{1/2}(\eta_{F2}) \right]$$

The drain current depends on m_{yy} , which is different for each type of valley.

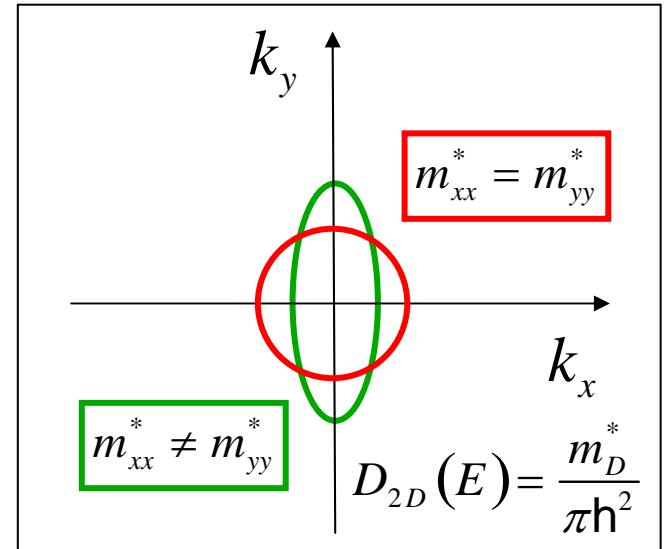
recall: carrier densities in 2D

To find the 2D carrier density, we integrate:

$$n_S^+(0) = \int_{\varepsilon_1(0)}^{\varepsilon_1(top)} \frac{D_{2D}(E)}{2} f_0(E_{F1}) dE$$

$$n_S^+(0) = \frac{N_{2D}}{2} \mathcal{F}_0(\eta_{F1})$$

$$N_{2D} = \frac{m_D^* k_B T}{\pi \hbar^2} \text{ #/cm}^2$$



$$D_{2D}(E) = g_V \frac{\sqrt{m_{xx}^* m_{yy}^*}}{\pi \hbar^2}$$

$$m_D^* = g_V \sqrt{m_{xx}^* m_{yy}^*}$$

example: (100) Silicon [100] transport

Drain current:

$$I_D = Wqg_V \left(\frac{m_{yy}^* k_B T}{2\pi\hbar^2} \right) \sqrt{\frac{2k_B T}{\pi m_{yy}^*}} \left[\mathcal{F}_{1/2}(\eta_{F1}) - \mathcal{F}_{1/2}(\eta_{F2}) \right]$$

Carrier density:

$$n_S(0) = \frac{N_{2D}}{2} \left[\mathcal{F}_0(\eta_{F1}) + \mathcal{F}_0(\eta_{F2}) \right]$$

$$N_{2D} = \frac{m_D^* k_B T}{\pi\hbar^2} \text{ \#/cm}^2$$

Velocity:

$$\langle v \rangle = \frac{I_D}{Wqn_S} = \sqrt{\frac{2k_B T}{\pi m_{xx}^*}} \frac{\left[\mathcal{F}_{1/2}(\eta_{F1}) - \mathcal{F}_{1/2}(\eta_{F2}) \right]}{\left[\mathcal{F}_0(\eta_{F1}) + \mathcal{F}_0(\eta_{F2}) \right]}$$

$$m_D^* = g_V \sqrt{m_{xx}^* m_{yy}^*}$$

$$m_C^* = m_{xx}^*$$

example: (100) Silicon [100] transport

the unprimed subbands will be the lowest because: $m_{conf}^* = m_l^*$

$$m_{xx}^* = m_{yy}^* = m_t^* = 0.19m_0 \quad m_D^* = 2m_t^* \quad m_C^* = m_t^*$$

the primed subbands are higher in energy because: $m_{conf}^* = m_t^*$

$$m_{xx}^* \neq m_{yy}^* \quad m_D^* = 4\sqrt{m_t^* m_l^*} \quad m_C^* = 4 \left[m_t^{-1/2} + m_l^{-1/2} \right]^{-2}$$

more generally (for ellipsoidal energy bands)

For arbitrary crystallographic orientations with different confinement and transport directions, there will be different degeneracy factors, and different effective masses, $m_{xx}^*, m_{yy}^*, m_{zz}^*$

In each case, the appropriate density-of-states and conductivity effective masses can be obtained.

For example, the standard transport direction for (100) Si is [110]. For the unprimed subbands, things don't change, but for the primed bands, the conductivity mass changes to: $m_c^* = 2m_t^* m_l^* / (m_t^* + m_l^*)$

references

Anisur Rahman, Mark S. Lundstrom, and Avik Ghosh, “Generalized Effective Mass Approach for Cubic Semiconductor n-MOSFETs on Arbitrarily Oriented Substrates,” *J. Appl. Phys.*, **97**, 053702, March 1, 2005.

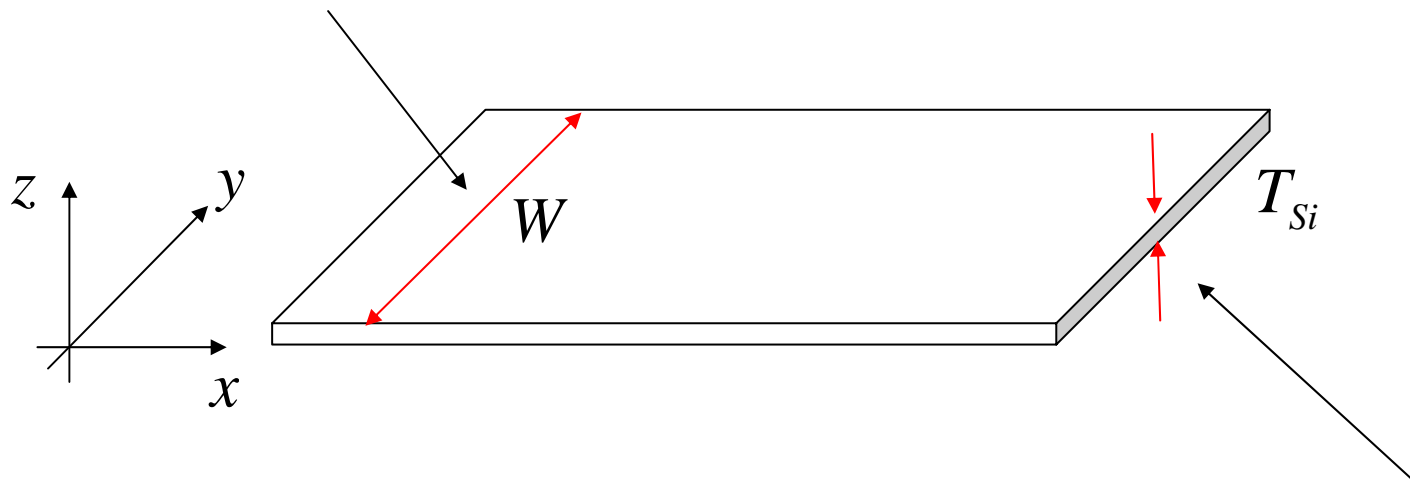
Marco De Michielis, David Esseni, and Francesco Driussi, “Analytical Models for the Insight Into the Use of Alternative Channel Materials in Ballistic nano-MOSFETs,” *IEEE Trans. Electron Dev.*, **54** (1), pp. 115-123, 2007.

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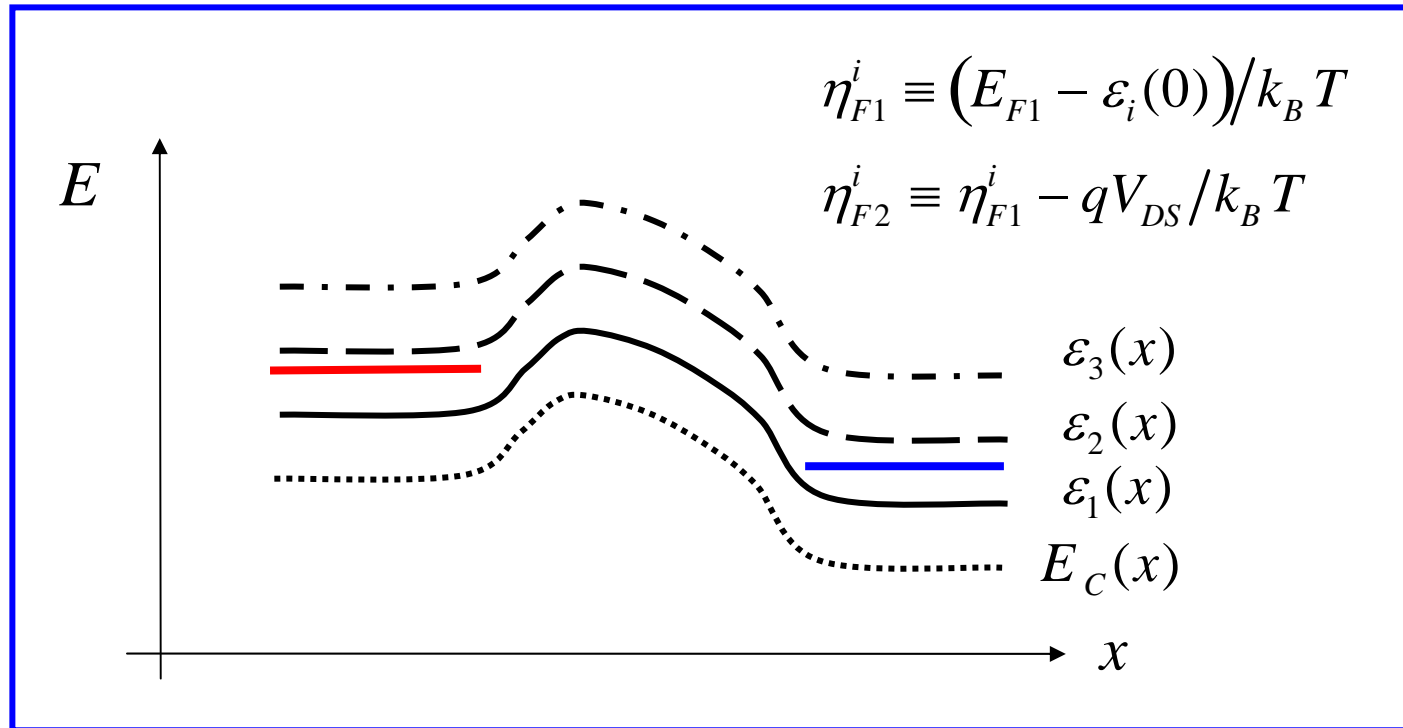
subbands and modes

For each subband associated with confinement in the z-direction, there is also a set of subbands (modes) associated with confinement in the y-direction.



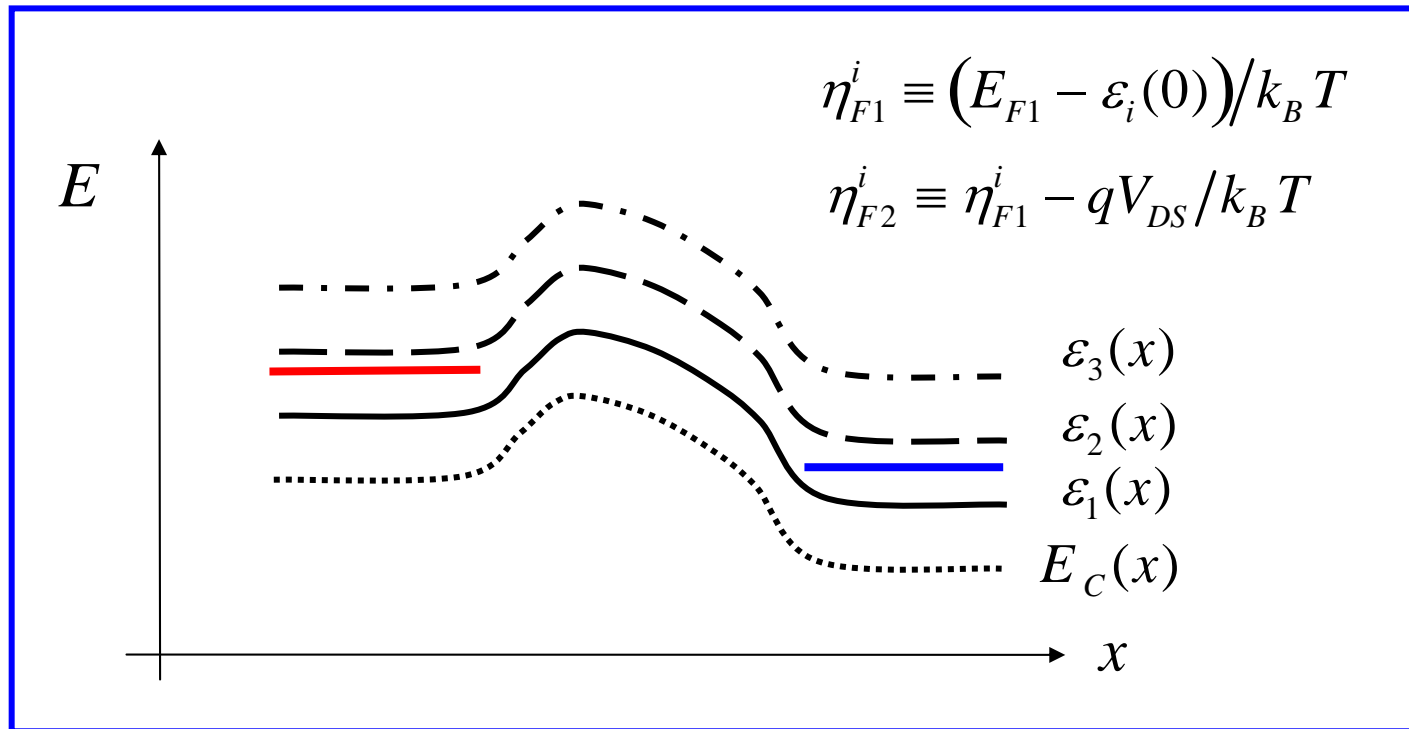
There is a set of subbands associated with confinement in the z-direction.

multiple subbands



Each subband associated with confinement in the z-direction has many **independent transverse modes** (assuming there is no potential variation in the y-direction, the width of the MOSFET).

multiple subbands



Each subband associated with confinement in the z-direction can be treated as an **independent conduction channel** (with many transverse modes) as long as the potential variation in the x-direction is gentle.

treating multiple subbands

For independent subbands, we can simply add up the contributions to the current and carrier density from each subband.

$$n_S(0) = \sum_i \frac{N_{2D}^i}{2} \left[\mathcal{F}_0(\eta_{F1}^i) + \mathcal{F}_0(\eta_{F2}^i) \right]$$

$$I_D = Wq \sum_i \left(\frac{N_{2D}^i}{2} v_T^i \right) \left[\mathcal{F}_{1/2}(\eta_{F1}^i) - \mathcal{F}_{1/2}(\eta_{F2}^i) \right]$$

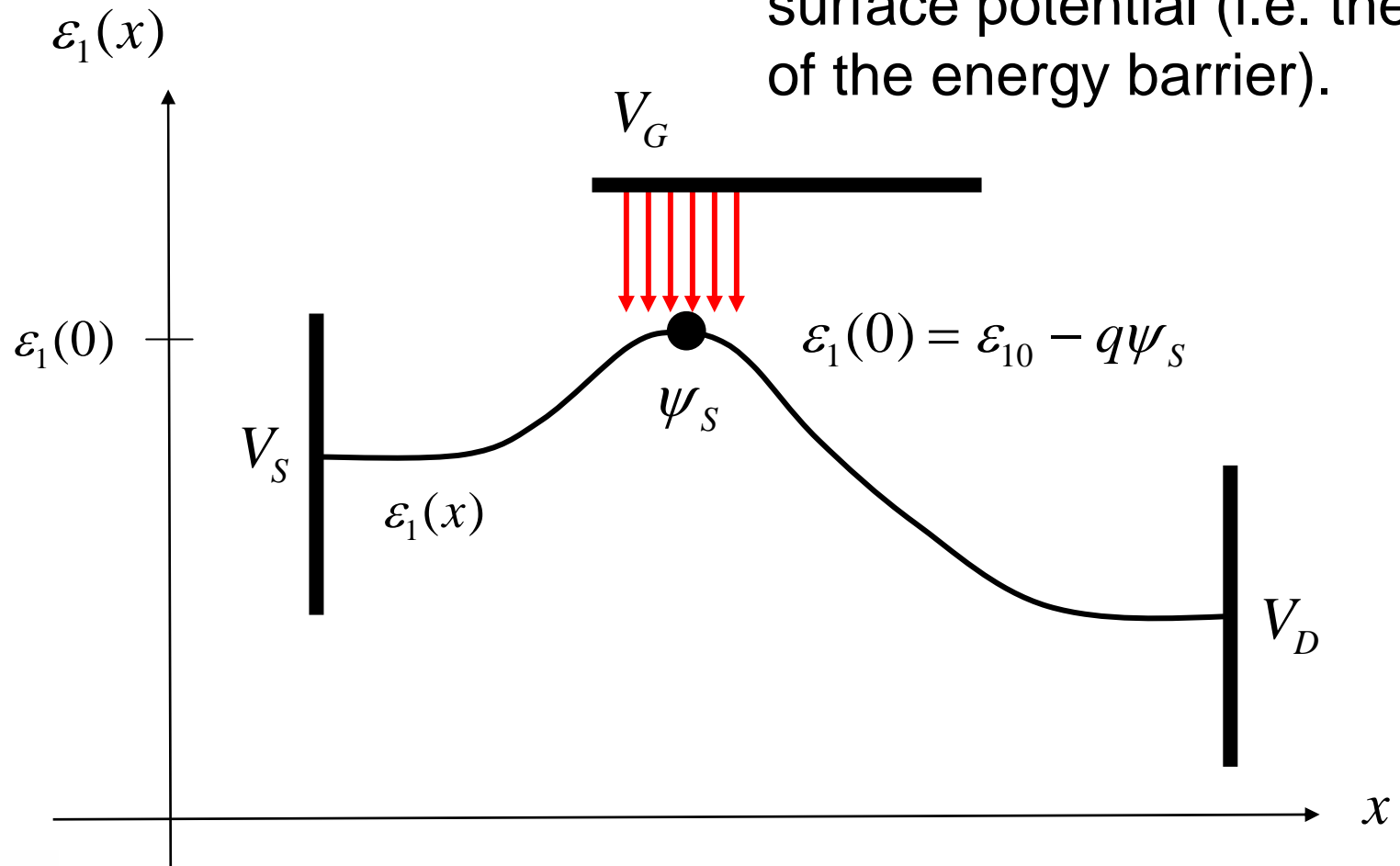
$$\eta_{F1}^i \equiv (E_{F1} - \varepsilon_i(0)) / k_B T \quad \eta_{F2}^i \equiv \eta_{F1}^i - qV_{DS} / k_B T$$

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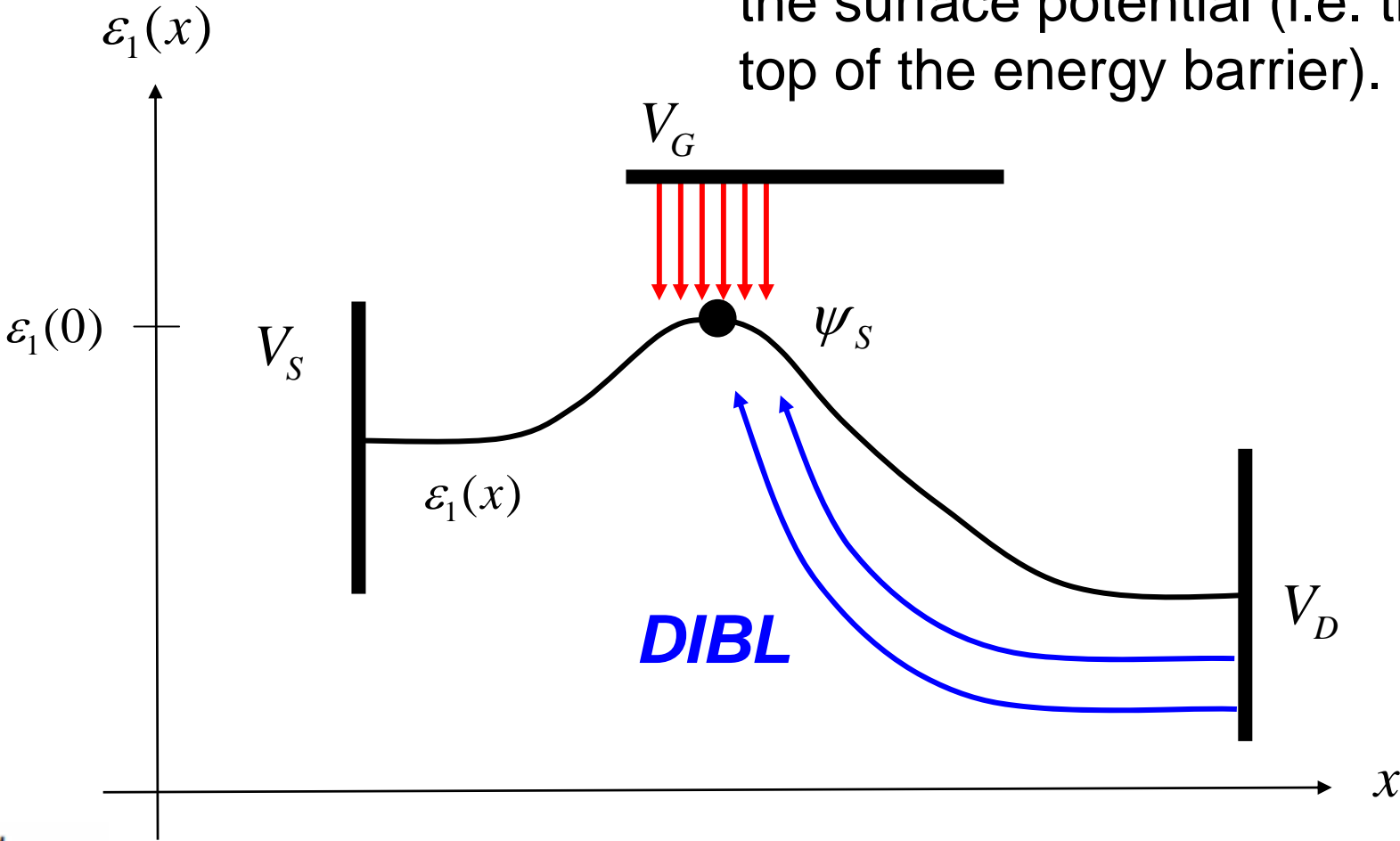
ideal MOS electrostatics

the **gate voltage** controls the surface potential (i.e. the top of the energy barrier).

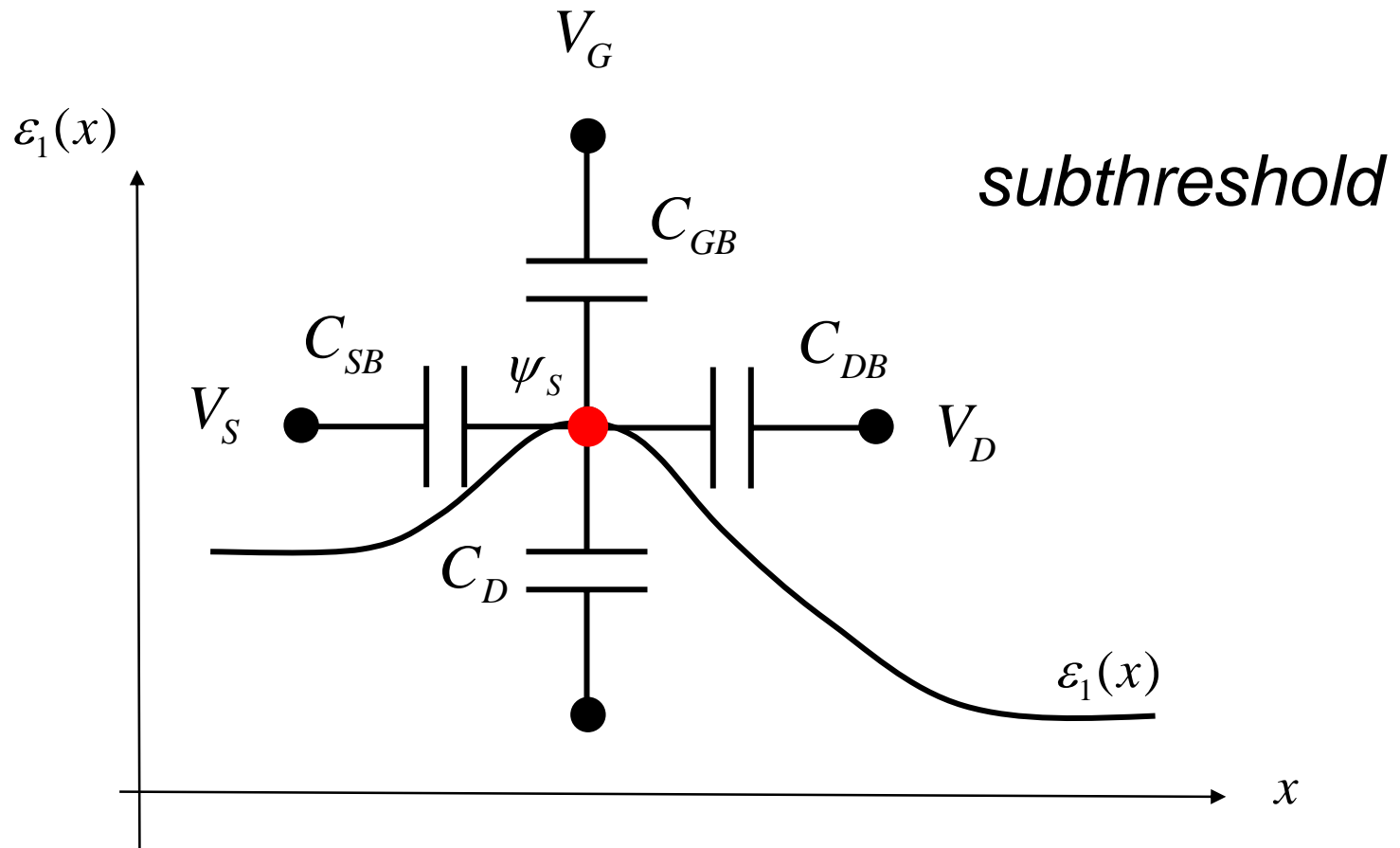


2D MOS electrostatics

*the **drain voltage** also affects the surface potential (i.e. the top of the energy barrier).*

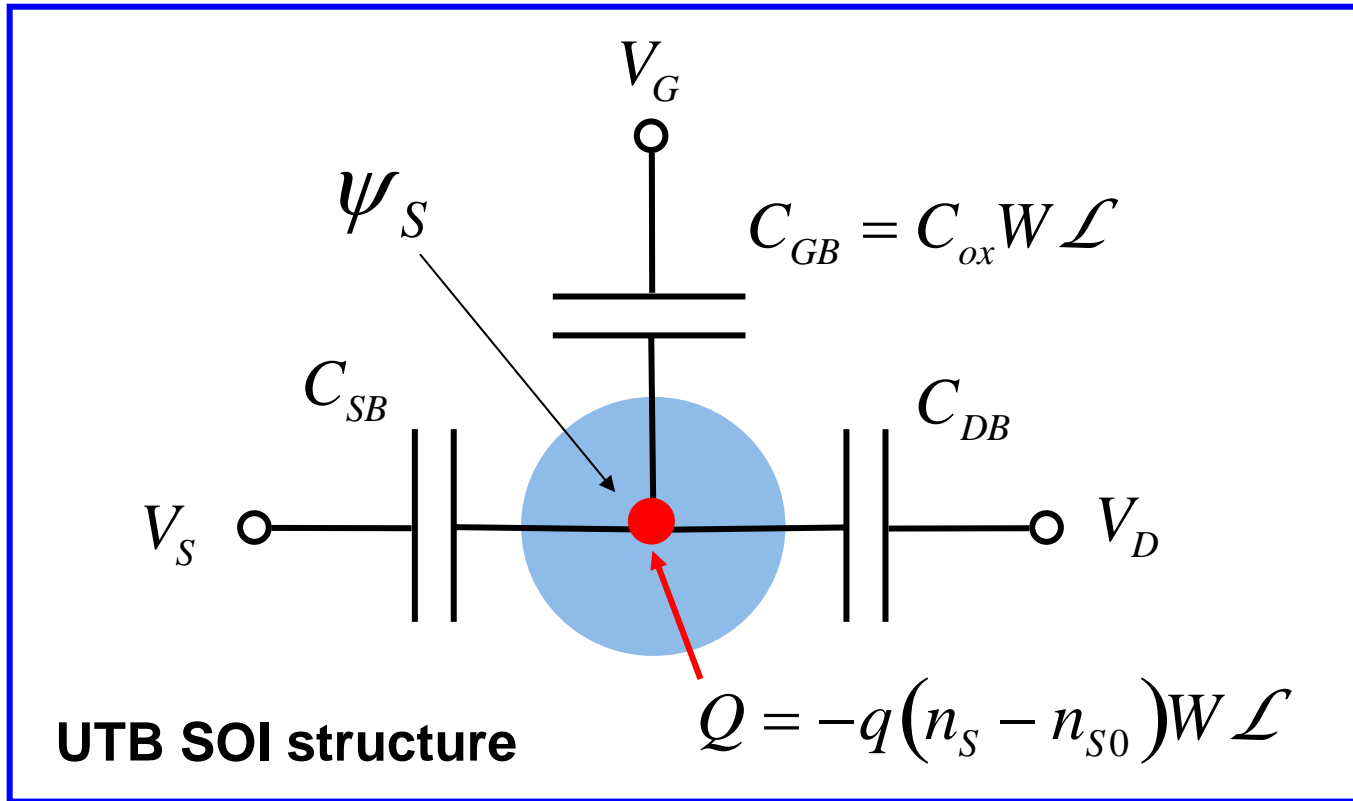


capacitor model for 2D electrostatics



C_D is the depletion capacitance of the semiconductor. If, for example, the MOSFET is an undoped, ultra-thin body structure, then there would be no depletion capacitance.

capacitor model (ii)



$$\psi_S = V_G \left(\frac{C_{GB}}{C_\Sigma} \right) + V_D \left(\frac{C_{DB}}{C_\Sigma} \right) + V_S \left(\frac{C_{SB}}{C_\Sigma} \right) - \frac{q[n_S(\psi_S) - n_{S0}]W \mathcal{L}}{C_\Sigma}$$

solving the capacitor model

$$\psi_S = V_G \left(\frac{C_{GB}}{C_\Sigma} \right) + V_D \left(\frac{C_{DB}}{C_\Sigma} \right) + V_S \left(\frac{C_{SB}}{C_\Sigma} \right) - \frac{q [n_S(\psi_S) - n_{S0}] W \mathcal{L}}{C_\Sigma} \quad (1)$$

$$n_S(0) = \frac{N_{2D}}{2} [\mathcal{F}_0(\eta_{F1}) + \mathcal{F}_0(\eta_{F2})]$$

$$\eta_{F1} \equiv [E_{F1} - \varepsilon_1(0)] / k_B T$$

$$\eta_{F2} = \eta_{F1} - qV_{DS} / k_B T$$

$$\varepsilon_1(0) = \varepsilon_{10} - q\psi_S$$

(ε_{10} is the value of $\varepsilon_1(0)$ when $\psi_S = 0$
i.e. 'flatband' conditions.)

Eqn. (1) is a nonlinear equation for ψ_S . It can be solved by iteration.

solving for I_D

$$\psi_S = V_G \left(\frac{C_{GB}}{C_\Sigma} \right) + V_D \left(\frac{C_{DB}}{C_\Sigma} \right) + V_S \left(\frac{C_{SB}}{C_\Sigma} \right) - \frac{q [n_S(\psi_S) - n_{S0}] W \mathcal{L}}{C_\Sigma} \quad (1)$$

$$\eta_{F1} \equiv [E_{F1} - \varepsilon_{10} + q\psi_S] / k_B T \quad \eta_{F2} = \eta_{F1} - qV_{DS} / k_B T$$

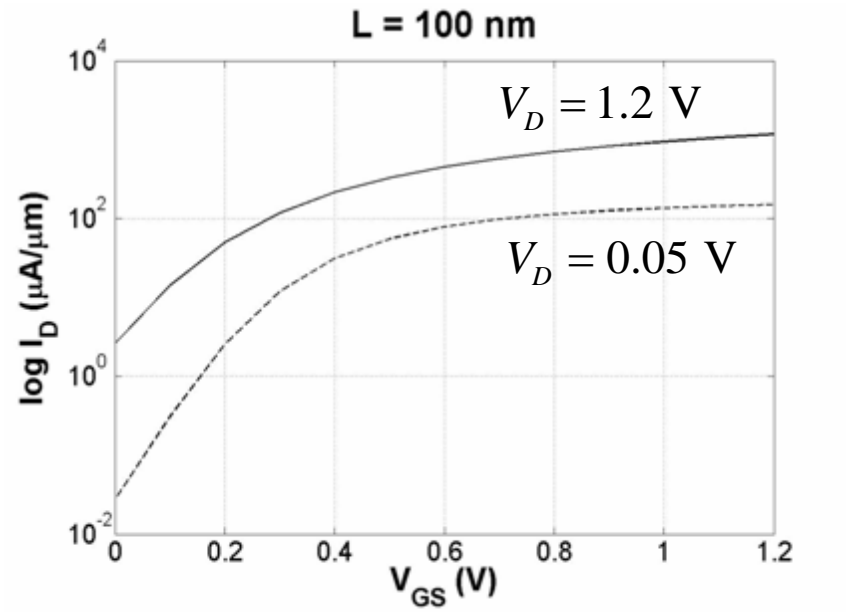
$$I_D = Wq \left(\frac{N_{2D}}{2} v_T \right) [\mathcal{F}_{1/2}(\eta_{F1}) - \mathcal{F}_{1/2}(\eta_{F2})] \quad (2)$$

For a given V_G and V_D ($V_S = 0$):

- 1) Solve (1) for ψ_S
- 2) Solve (2) for I_D

(~Treats 2D MOS electrostatics, above and below threshold.)

how do we determine the capacitors?



must specify:

$$C_{GB}$$

$$C_{DB}$$

$$C_{SB} \quad (\text{or } C_{\Sigma} = C_{GB} + C_{DB} + C_{SB})$$

can do this from measured or simulated data

how do we determine the capacitors?

under high drain bias:

$$I_D \approx Wq \frac{N_{2D}}{2} v_T \mathcal{F}_{1/2}(\eta_{F1})$$

under subthreshold conditions:

$$I_D \approx WqN_{2D}v_T e^{\eta_{F1}} \sim e^{(E_F - \varepsilon_1(0))/k_B T}$$

$$\varepsilon_1(0) = \varepsilon_{10} - q\psi_S$$

$$I_D \sim e^{q\psi_S/k_B T}$$

$$S = 2.3 \frac{C_\Sigma}{C_{GB}} (k_B T / q)$$

$$DIBL = \frac{C_{DB}}{C_{GB}}$$

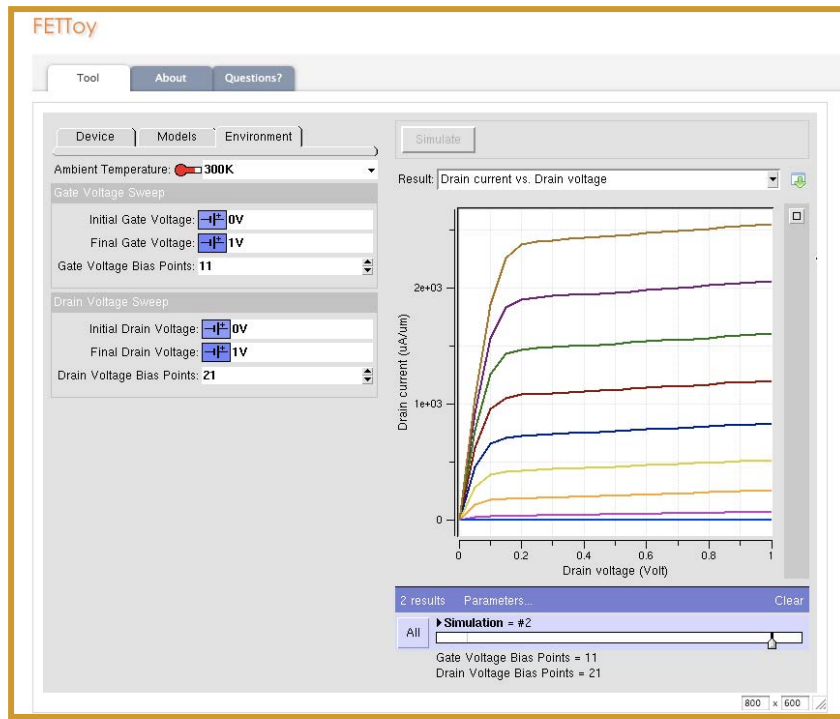
$$\alpha_G = \frac{C_{GB}}{C_\Sigma} \quad \alpha_D = \frac{C_{DB}}{C_\Sigma}$$

$$S = \frac{2.3(k_B T / q)}{\alpha_G}$$

$$DIBL = \frac{\alpha_D}{\alpha_G}$$

FETToy

The theory outlined here has been implemented in FETToy, a simulation tool that you can run on nanoHUB.org. You can also download the program to see how the theory is implemented.

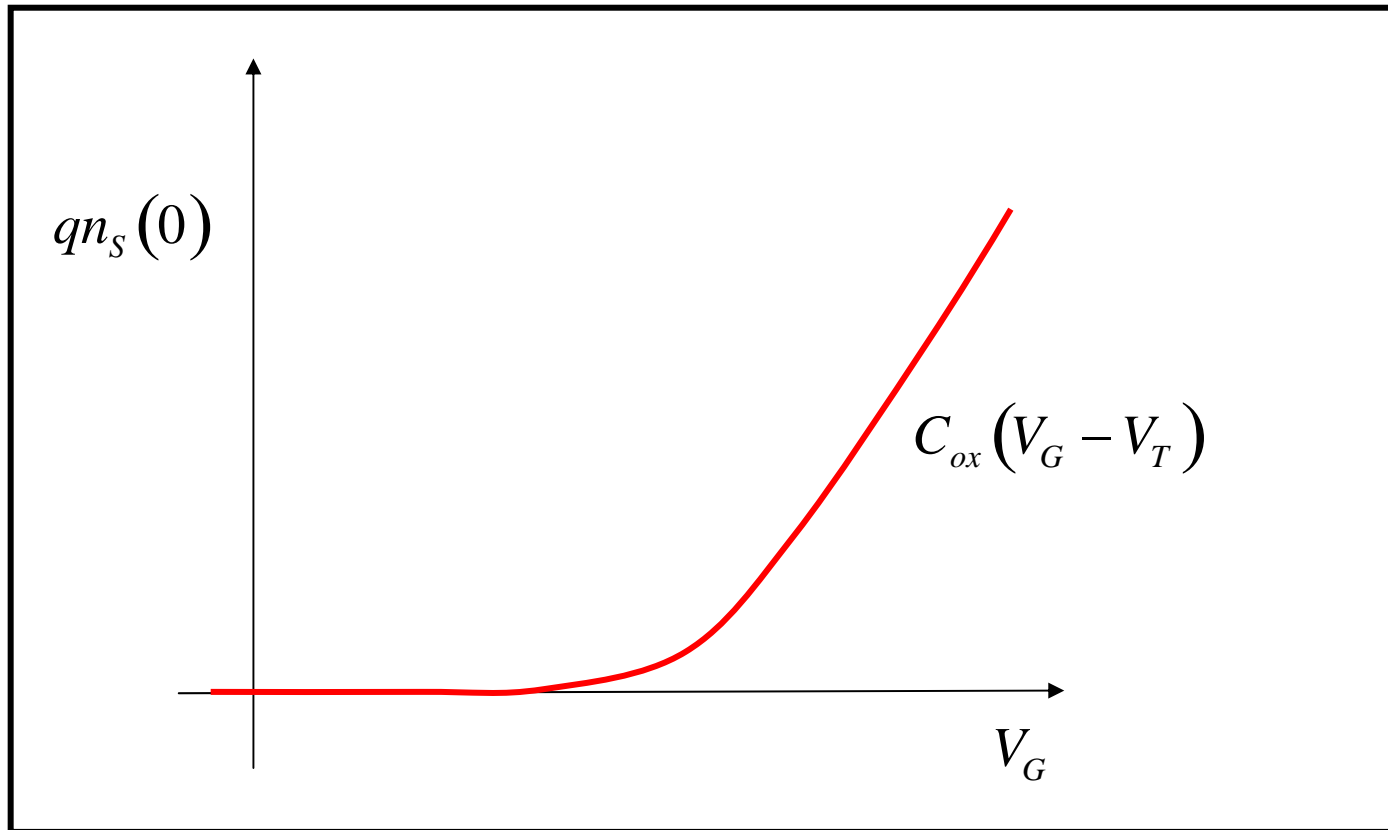


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an aside on MOS electrostatics

in part 1), we assumed ideal, 1D, MOS electrostatics:



an aside on MOS electrostatics (ii)

capacitor model:

$$\psi_S = V_G \left(\frac{C_{GB}}{C_\Sigma} \right) + V_D \left(\frac{C_{DB}}{C_\Sigma} \right) + V_S \left(\frac{C_{SB}}{C_\Sigma} \right) - \frac{q [n_S(\psi_S) - n_{S0}] W \mathcal{L}}{C_\Sigma}$$

1D MOS electrostatics:

$$\psi_S = V_G - \frac{q [n_S(\psi_S) - n_{S0}]}{C_{ox}} \quad (1)$$

also, for high drain bias:

$$n_S(0) = \frac{N_{2D}}{2} \mathcal{F}_0(\eta_{F1}) \quad (2)$$

Eqns. (1) and (2) can be solved for $\psi_S(V_G)$ and for $n_S(V_G)$.

(assuming strong carrier degeneracy)

an aside on MOS electrostatics (iii)

results:

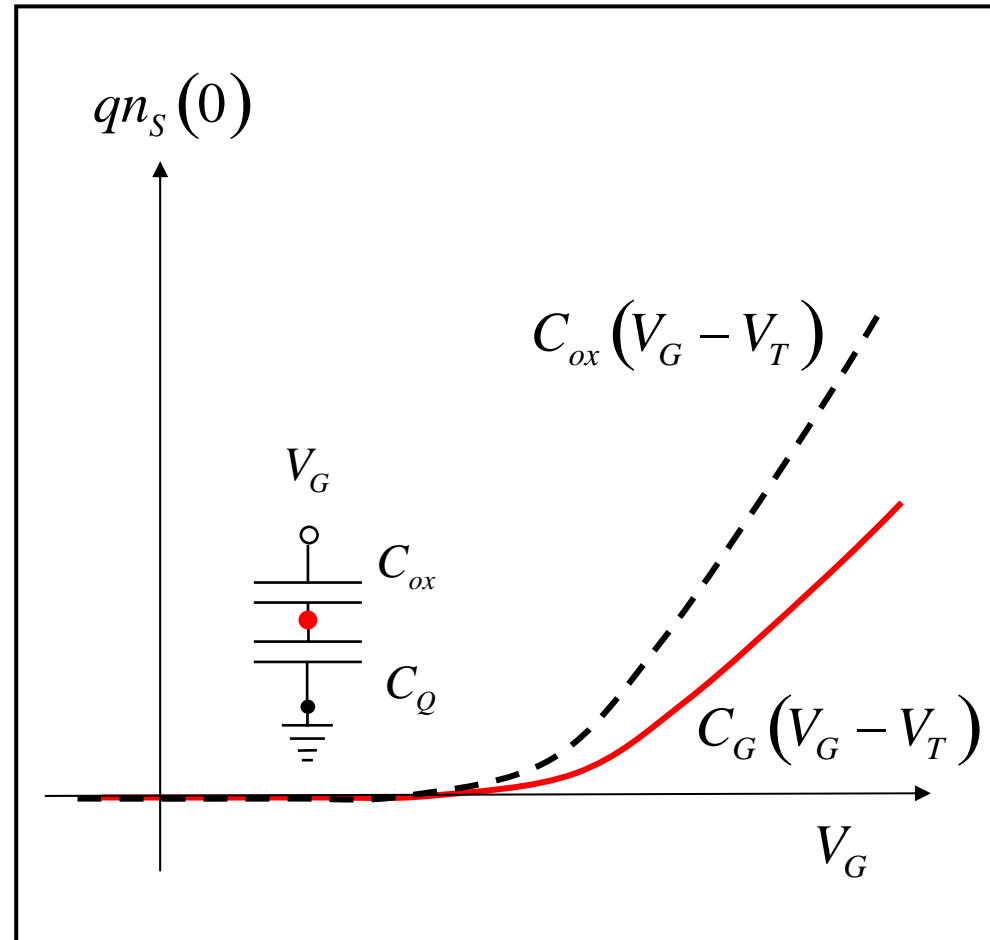
$$\psi_S = \psi_{S0} + \frac{V_G}{1 + C_Q/C_{ox}}$$

$$C_Q = \frac{q^2 m_D^*}{2\pi\hbar^2}$$

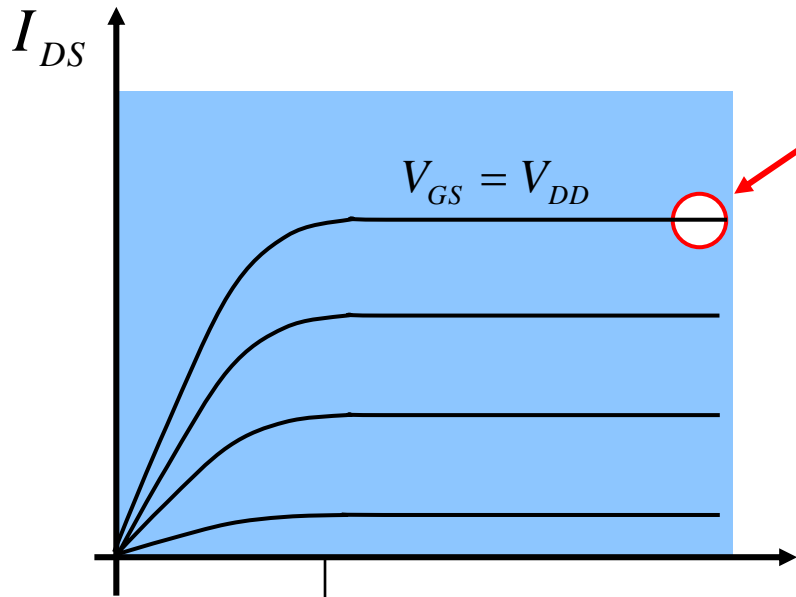
“quantum capacitance”

$$n_S = \frac{C_{ox} C_Q}{C_{ox} + C_Q} (V_G - V_T)$$

$$C_G = \frac{C_{ox} C_Q}{C_{ox} + C_Q}$$



an aside on MOS electrostatics (iv)



$$I_{ON} = WC_G \mu_P (V_{GS} - V_T)$$

$$C_G = \frac{C_{ox} C_Q}{C_{ox} + C_Q}$$

$$C_Q = \frac{q^2 m_D^*}{2\pi \hbar^2}$$

more generally:

$$C_Q \rightarrow C_S \equiv \frac{\epsilon_{ox}}{t_{inv}}$$

an aside on MOS electrostatics (v)

$$qn_s(0) = C_G (V_G - V_T) = \frac{C_{ox} C_Q}{C_{ox} + C_Q} (V_G - V_T) \quad C_Q = \frac{q^2 m^*}{2\pi\hbar^2}$$

$$I_D = WQ_I(0) \langle v(0) \rangle \quad v_{\rho} \equiv \sqrt{\frac{2k_B T}{\pi m^*} \frac{\mathcal{F}_{1/2}(\eta_{F1})}{\mathcal{F}_0(\eta_{F1})}}$$

Small effective mass means high injection velocity. :-)

Small effective mass means low inversion layer density. :-)

“density-of-states bottleneck”

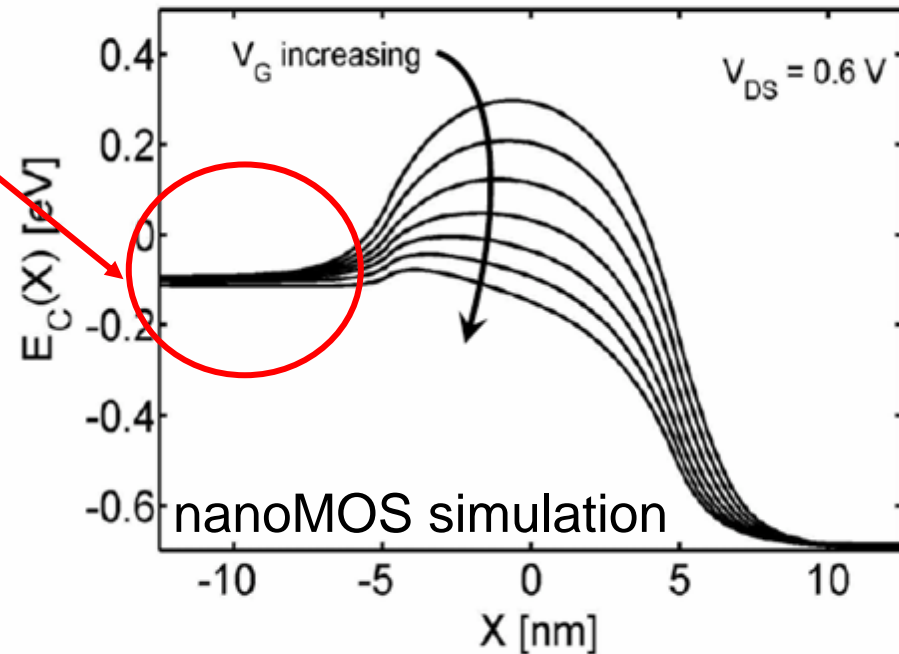
M. V. Fischetti and S. E. Laux, “Monte Carlo simulation of transport in technologically significant semiconductors of the diamond and zinc-blende structures-Part II: Submicrometer MOSFET’s,” *IEEE Trans. Elect. Dev.*, **38**, 1991.

P. M. Solomon, and S.E. Laux, “The ballistic FET: Design, capacitance and speed limit,” in *IEDM Tech. Dig.*, Dec. 2001.

source electrostatics

Note that the conduction band in the source drops slightly as V_{GS} increases. Why?

The reason has to do with the electrostatics of the source under ballistic conditions.

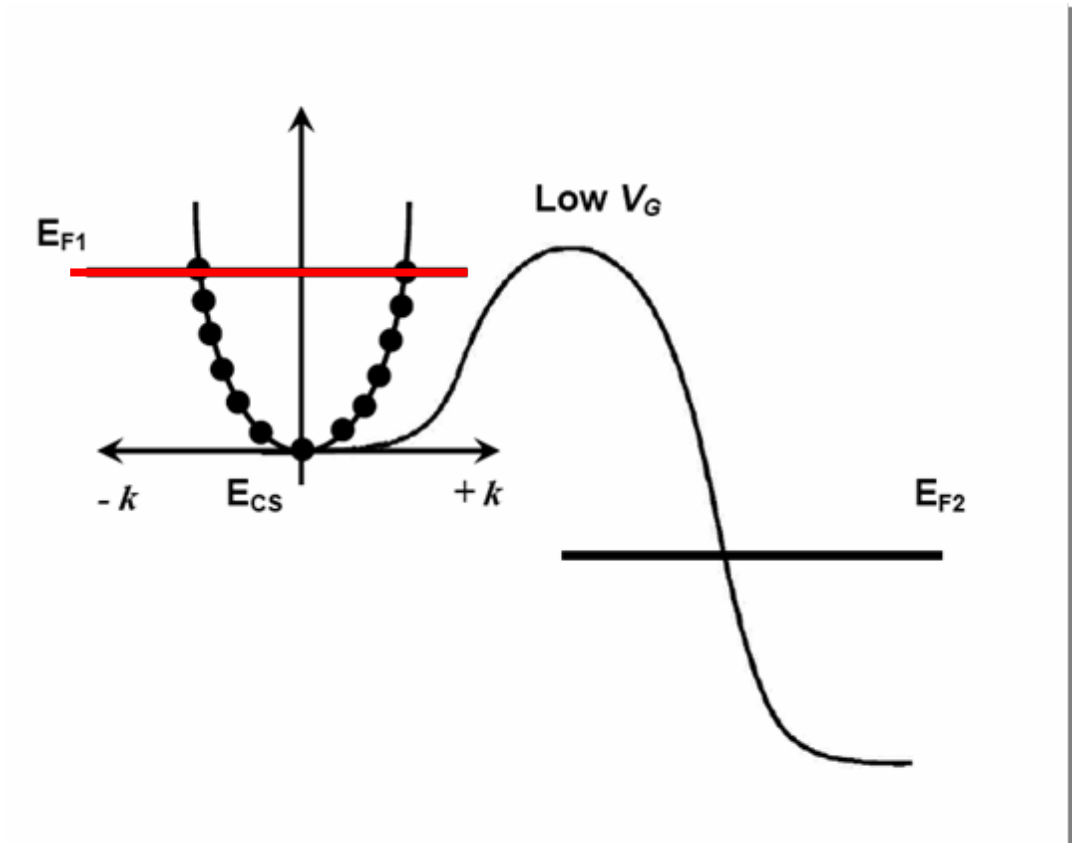


A. Rahman, et al., *IEEE TED*, **50**, 1853, 2003.

source electrostatics (ii)

Electrons are injected from the contact into the ballistic source. Most reflect off of the barrier, so $+k$ and $-k$ states are occupied.

The total electron density in the source is equal to the total dopant density.

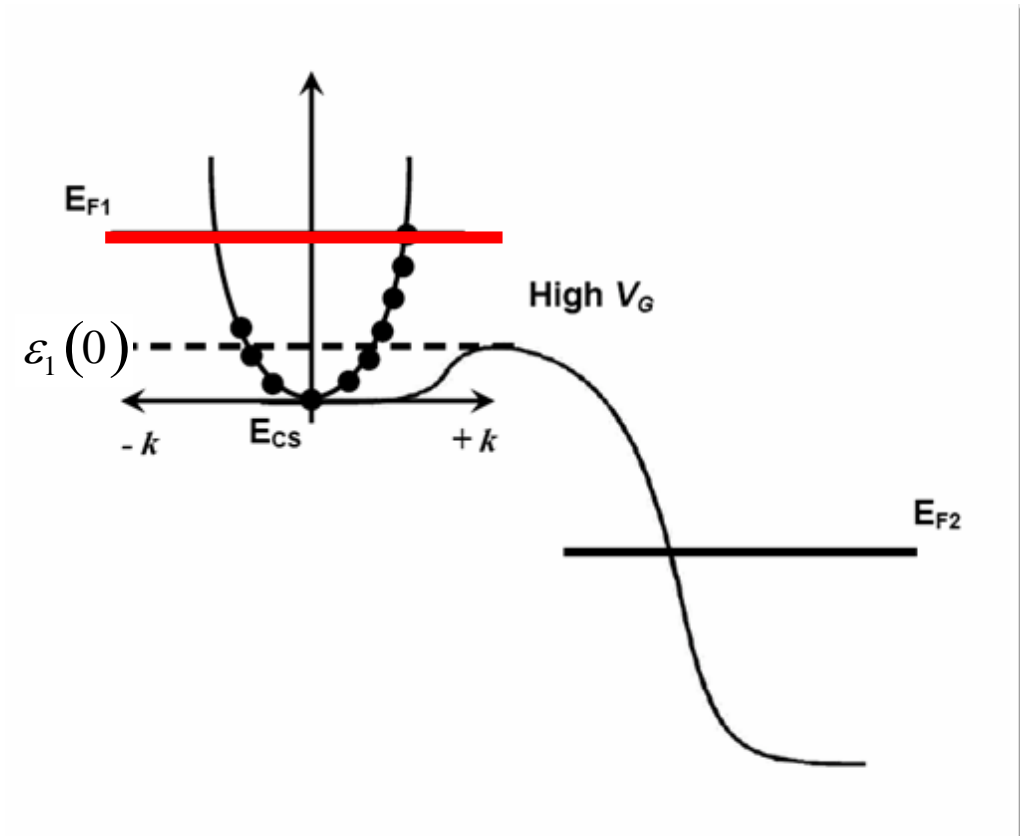


A. Rahman, et al., *IEEE TED*, **50**, 1853, 2003.

source electrostatics (iii)

Under high gate bias, less reflection occurs and fewer $-k$ states are occupied.

This cannot be the correct band diagram, because the total electron charge is now less than the total dopant charge.

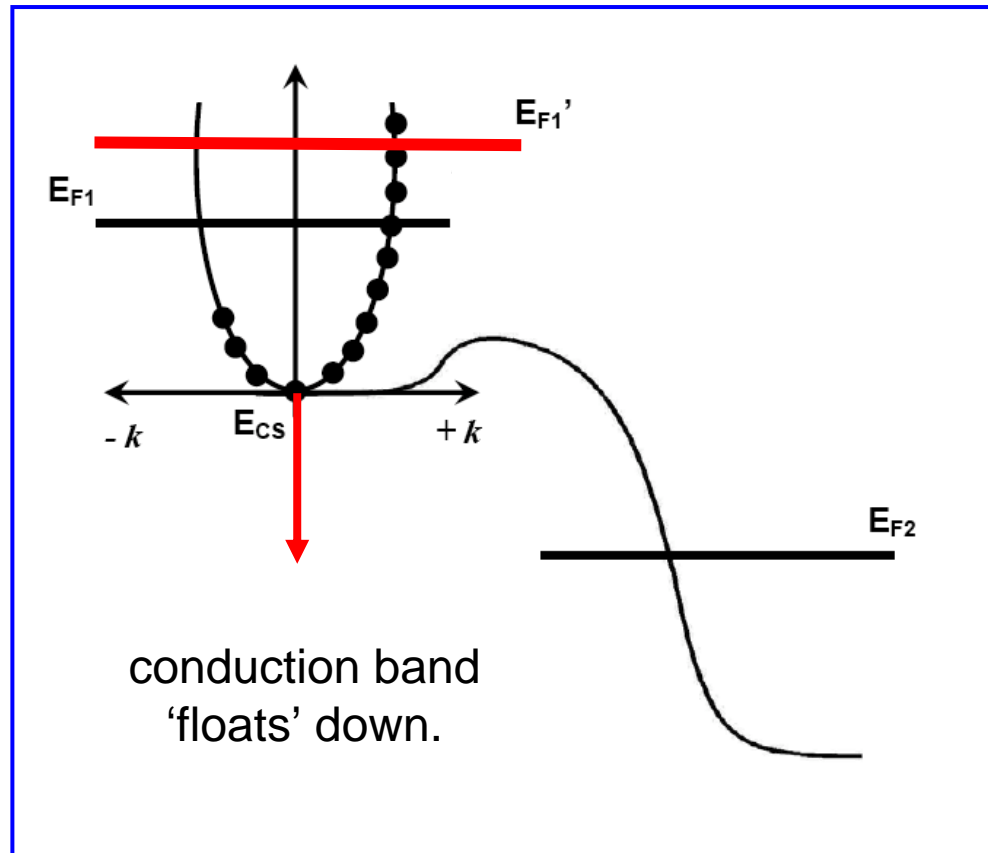


A. Rahman, et al., *IEEE TED*, **50**, 1853, 2003.

source electrostatics (iv)

To satisfy the Poisson equation, the conduction band in the source moves down to let more +v electrons in.

Charge balance in the source has been restored, but the top of the barrier is now lower, so I_D is higher.



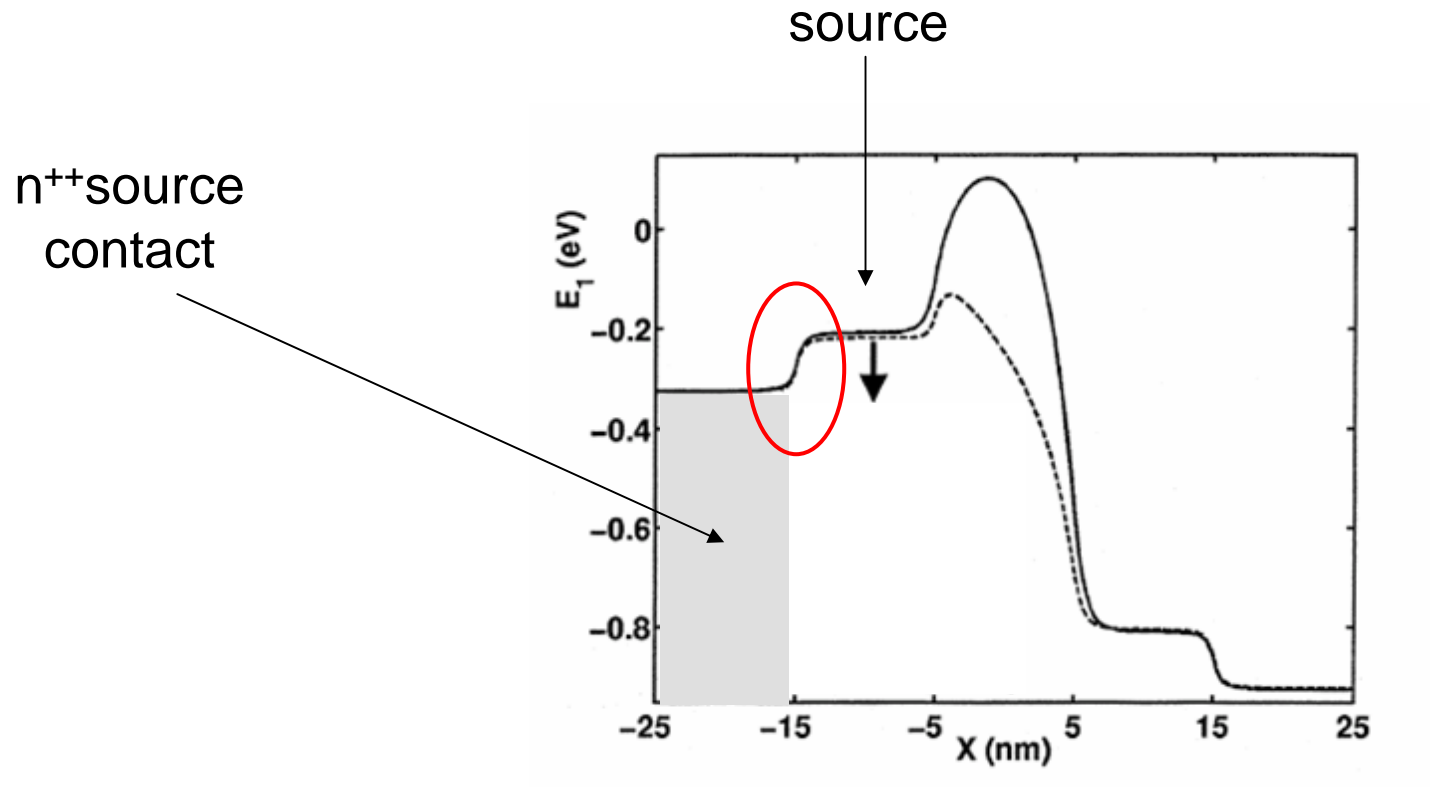
A. Rahman, et al., *IEEE TED*, **50**, 1853, 2003.

source electrostatics (v)

For a discussion of how to treat these “floating source” effects in our “top of the barrier model,” see:

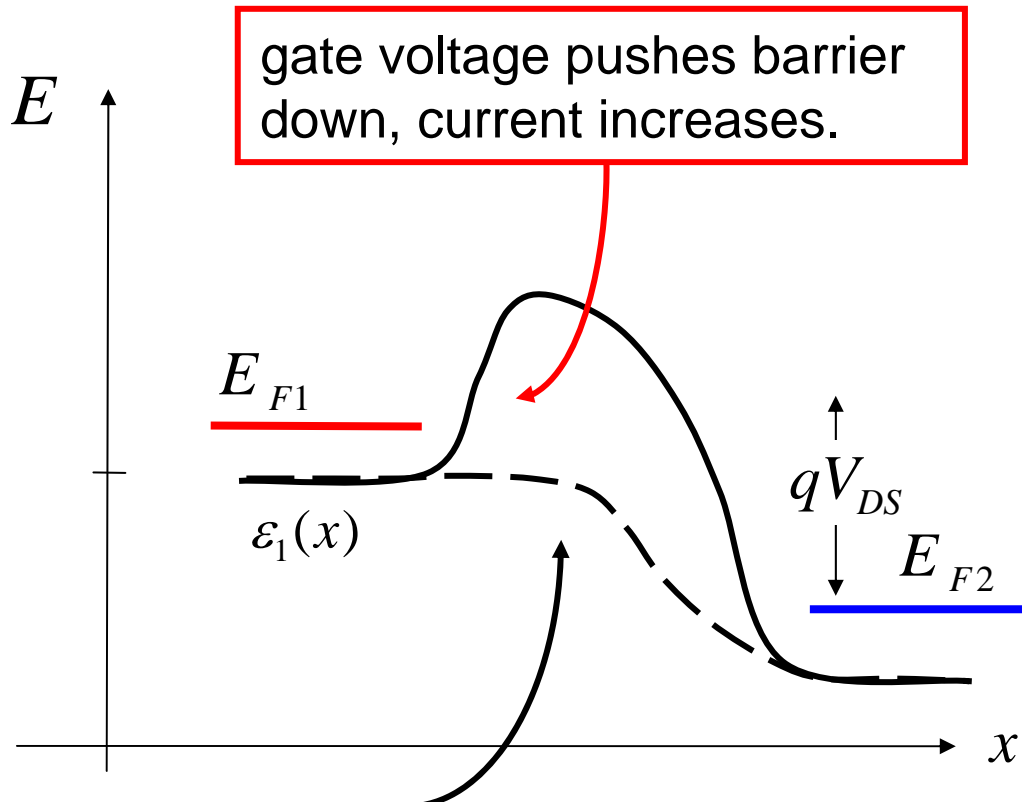
Anisur Rahman, Jing Guo, Supriyo Datta, and Mark Lundstrom, “Theory of Ballistic Nanotransistors,” *IEEE Trans. Electron. Dev.*, Nanoelectronics, **50**, pp. 1853-1864, 2003.

numerical simulation



Zhibin Ren, Ramesh Venugopal, Sebastien Goasguen, Supriyo Datta, and Mark S. Lundstrom, "nanoMOS 2.5: A Two-Dimensional Simulator for Quantum Transport in Double-Gate MOSFETs," *IEEE Trans. Elec. Dev.*, **50**, pp. 1914-1925, 2003.

“source exhaustion”



Another view: The charge in the channel cannot be greater than the charge in the source.

$$Q_I(\text{max}) = qN_{DS}x_j$$

This effect can be important when the source is not heavily doped, for example, in a III-V FET.

at high gate voltage, barrier is eliminated, g_m plummets.

source exhaustion comments

Source exhaustion, as I have described is it is purely electrostatic effect that is present in a ballistic or drift-diffusion model.

Another effect, “source starvation,” which has to do with the injection of carriers from the 3D contact to the 2D channel, may also be important.

See:

M. Fischetti, T. O’ Reagan, S. Narayanan, C. Sachs, S. Jin, J. Kim, and Y. Zhang, “Theoretical study of some physical aspects of electronic transport in nMOSFETs at the 10-nm gate-length,” *IEEE Trans. Elect. Dev.*, **54**, 2007.

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summary

We have generalized

$$I_D = WC_{ox} (V_{GS} - V_T) \beta \left[\frac{1 - \mathcal{F}_{1/2}(\eta_{F2}) / \mathcal{F}_{1/2}(\eta_{F1})}{1 + \mathcal{F}_0(\eta_{F2}) / \mathcal{F}_{10}(\eta_{F1})} \right]$$

to include 2D and subthreshold electrostatics as well as the effect of the quantum capacitance above threshold:

$$\psi_S = V_G \left(\frac{C_G}{C_\Sigma} \right) + V_D \left(\frac{C_D}{C_\Sigma} \right) + V_S \left(\frac{C_S}{C_\Sigma} \right) - \frac{qn_S(\psi_S)}{C_\Sigma}$$

$$I_D = Wq \left(\frac{N_{2D}}{2} v_T \right) \left[\mathcal{F}_{1/2}(\eta_{F1}) - \mathcal{F}_{1/2}(\eta_{F2}) \right]$$

and we discussed some of the implications.

suggested exercise: subthreshold conduction

$$\psi_S = V_G \left(\frac{C_{GB}}{C_\Sigma} \right) + V_D \left(\frac{C_{DB}}{C_\Sigma} \right) + V_S \left(\frac{C_{SB}}{C_\Sigma} \right) - \frac{q [n_S(\psi_S) - n_{S0}] W \mathcal{L}}{C_\Sigma}$$

$$\eta_{F1} \equiv [E_{F1} - \varepsilon_{10} + q\psi_S] / k_B T \quad \eta_{F2} = \eta_{F1} - qV_{DS} / k_B T$$

$$I_D = Wq \left(\frac{N_{2D}}{2} v_T \right) [\mathcal{F}_{1/2}(\eta_{F1}) - \mathcal{F}_{1/2}(\eta_{F2})]$$

Exercise: Simplify for 1D electrostatics and subthreshold conduction and derive the subthreshold I-V characteristics of a ballistic MOSFET.

suggested exercise: bulk MOSFET

$$\psi_S = V_G \left(\frac{C_{GB}}{C_\Sigma} \right) + V_D \left(\frac{C_{DB}}{C_\Sigma} \right) + V_S \left(\frac{C_{SB}}{C_\Sigma} \right) - \frac{q [n_S(\psi_S) - n_{S0}] W \mathcal{L}}{C_\Sigma}$$

$$\eta_{F1} \equiv [E_{F1} - \varepsilon_{10} + q\psi_S] / k_B T \quad \eta_{F2} = \eta_{F1} - qV_{DS} / k_B T$$

$$I_D = Wq \left(\frac{N_{2D}}{2} v_T \right) [\mathcal{F}_{1/2}(\eta_{F1}) - \mathcal{F}_{1/2}(\eta_{F2})]$$

Exercise: Repeat the derivation and develop a top of the barrier model for a bulk MOSFET.